

**TOREX SEMICONDUCTOR LTD.**  
Quality Assurance Dept.

## Composition Table

Product(Pb-free): XC6120xxxxHR-G  
Typical Mass: 2.5 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.099	Silicon	39700	7440-21-3
	-	Arsenic	2	7440-38-2
Lead pad	0.491	Nickel	196400	7440-02-0
	0.023	Silver	9100	7440-22-4
	0.005	Gold	2000	7440-57-5
Die attach	0.014	Epoxy Resin	5400	—
	0.011	Silica	4500	60676-86-0
Bonding wire	0.023	Gold	9100	7440-57-5
Resin	1.606	Silica	642300	60676-86-0
	0.091	Epoxy Resin	36600	—
	0.082	Phenol Resin	32800	—
	0.055	Metal Hydroxide	22100	—

\* The component composition is based on the information provided by raw material vender.

\* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

\* Any indication "-" in CAS number means "confidential."